









Release Date: 22 March 2017 Version: A1.0

PRODUCT DATASHEET



- ► PCB Reverse Mount
- ► 1206RV 1.1t Series
- ► Red (631nm) / Green (571nm)

NOD39S42RV



1206RV 1.1t Series

APPLICATIONS:

- Indication Light
- Switch light
- Dashboard
- Keyboard
- **Consumer Goods**

1206RV 1.1t Series Compliant





FEATURES:

- Package: PCB Reverse Mount SMT Package Duo Colours
- Forward Current: 20/20mA* Forward Voltage (typ.): 2.0/2.0V
- Luminous Intensity (typ.): 45/35mcd@20mA
- Colour: Red/Green Wavelength: 631/571nm
- Viewing angle: 130/130°
- **Materials:**
 - Die: AlGaInP/AlGaInP Resin: Epoxy (Water Clear) Operating Temperature: -30~+85°C
- Storage Temperature: -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **Dominant Wavelength**
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with 3000/reel, ø180mm (7")

^{*} in the order of Red/Green



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30/30*	mA
Peak Forward Current Duty 1/10, Pulse Width 0.1mS	I _{FP}	80/80	mA
Reverse Voltage0	V_R	5/5	V
Reverse Current @5V	I _R	10/10	μΑ
Power Dissipation	PD	75/75	mW
Operating Temperature	T _{OPR}	-30~+85	°C
Storage Temperature	T _{STG}	-40~+85	°C

^{*} in the order of Red/Green

Electrical & Optical Characteristics (Ta=25°C)

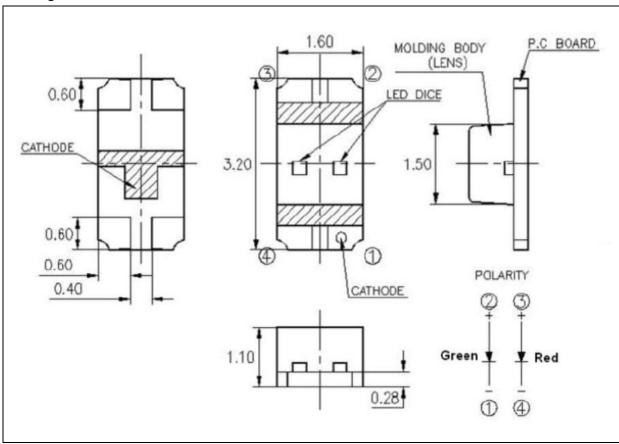
Parameter Symbol		Values			Unit	Test
Parameter	Parameter Symbol		Тур.	Max.	UIII	Condition
Forward Voltage	VF		2.0/2.0	2.4/2.4	V	I _F =20mA
Luminous Intensity	I _V	18/18	45/35		mcd	I _F =20mA
Dominant Wavelength	λ_{D}		631/571		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		20/15		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		130/130		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



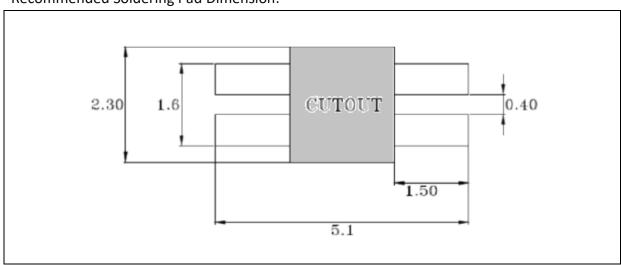
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
Red	1.7	2.4	V
Green	1.7	2.4	V

Luminous Intensity Classifications (I_F = 20mA):

Со	de	Min.	Max.	Unit
	M	18	28	
Red	N	28	45	mad
Red	Р	45	71	mcd
	Q	71	112	

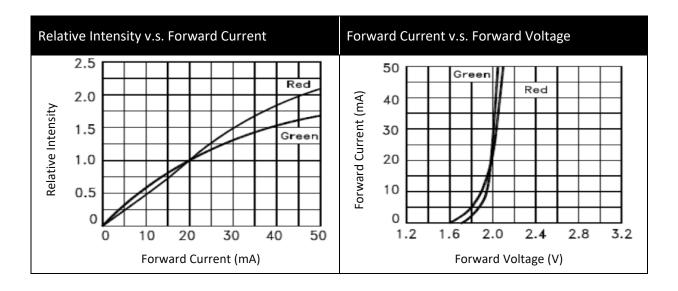
	М	18	28	
Croon	N	28	45	mad
Green	Р	45	71	mcd
	Q	71	112	

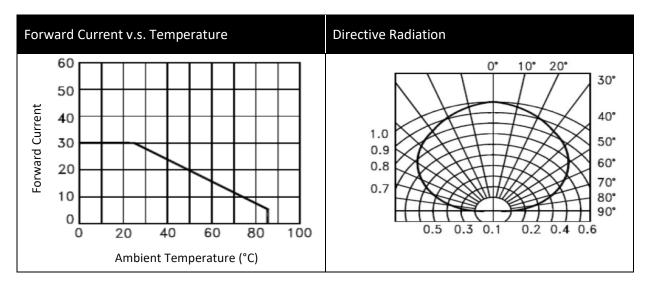
Dominant Wavelength Classifications (I_F = 20mA):

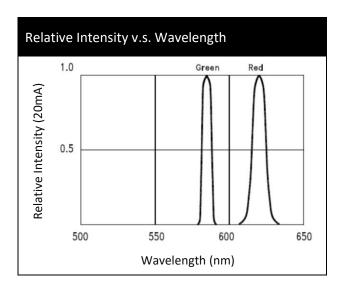
Code	Min.	Max.	Unit
Red	624	637	nm
Green	567	577	nm



ELECTRO-OPTICAL CHARACTERISTICS:



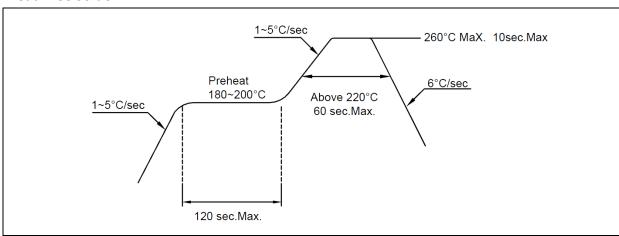






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



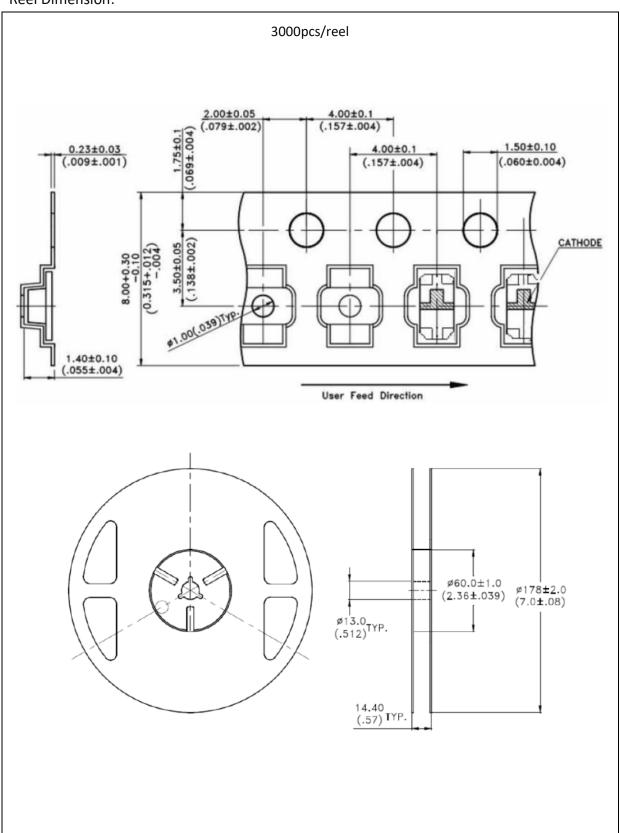
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~35°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

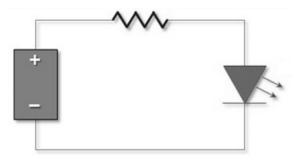
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	22/03/2017	Datasheet set-up.